

Hi-performance No-clean Solder Paste

SE5-M953iD & SS5-M953iD

■ Feature

- 1) Homogeneous mixture of specially formulated flux with rigidly classified solder powder ensures outstanding continual dispensability.
- 2) Carefully selected thixotropic materials ensure excellent slump resistivity and significantly reduce occurrence of bridging and solder beading.
- 3) Specially developed flux system ensures both extremely high reliability and superior solder wettability.
- 4) Extremely long tack time offers wide process window.
- 5) Low color flux residue offers superior cosmetic appearance.

■ Specifications

Application		Dispensing	
Products		SE5-M953iD (SS5-M953iD)	
Alloy	Composition (%)	Sn63, Pb37 (Sn62, Pb36, Ag2)	
	Shape	Spherical	
	Particle size (μm)	20 – 38	
Flux	Halide content (%)	0.0	
	surface insulator resistance * ¹	Initial value (Ω)	$> 1 \times 10^{12}$
		After humidification (Ω)	$> 1 \times 10^{11}$
	Aqueous solution resistivity* ² (Ω cm)	$> 5 \times 10^4$	
Flux type		ROL0	
Product	Flux content (%)	13	
	Viscosity* ³ (Ps)	800	
	Copper plate corrosion* ⁴	Passed	
	Solder spread factor (%)	90	
	Tack time	> 24 hours	
	Shelf life (below 10°C)	6 months	

1. SIR 40°C × 90%RH × 96Hr
2. Aqueous solution resistivity In accordance with MIL specifications.
3. Viscosity Malcom spiral type viscometer, PCU-2 at 25°C 10rpm
4. Copper plate corrosion In accordance with JIS.

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